

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takashi NAKANO	08/08/2011
Yukio TAMAI	08/08/2011
Nobuyoshi AWAYA	08/08/2011
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13215594
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OP \$40.00 13215594

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PATENT
 REEL: 026791 FRAME: 0949

ASSIGNMENT OF PATENT APPLICATION

(Inventors) **Takashi NAKANO**
 Yukio TAMAI
 Nobuyoshi AWAYA

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(Assignee) **SHARP KABUSHIKI KAISHA**

(Address) (of 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan
(hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions, and for the country of

(Other (in the invention, and all application for patent and any Letters Patent which
Countries) may be granted therefore, known as

(Title) **SEMICONDUCTOR MEMORY DEVICE**

(Case No. -)

for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed (on or has already filed in

(U.S. appln. Serial No. , filed on).

The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date 08/08/2011 Signature of inventor (Takashi Nakano
Takashi NAKANO

Date 08/08/2011 Signature of inventor (Yukio Tamai
Yukio TAMAI

Date 08/08/2011 Signature of inventor (Nobuyoshi Awaya
Nobuyoshi AWAYA

Date _____ Signature of inventor (_____

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Date _____ Signature of inventor (_____

Date _____ Signature of inventor (_____

Date _____ Signature of inventor (_____

Date _____ Signature of inventor (_____

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Date _____ Signature of inventor (_____

Date _____ Signature of inventor (_____

Witnessed by: _____ Date _____

Witnessed by: _____ Date _____

Witnessed by: _____ Date _____